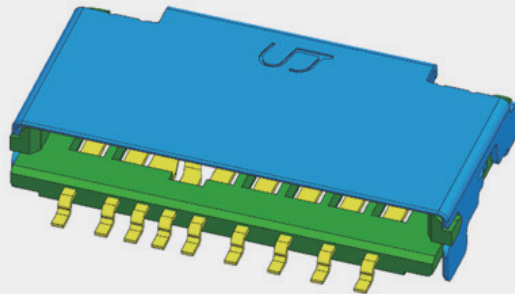


SIM and Memory Card Socket Connector



Applications | Mobile phone, Computer, Laptop, Medical equipment, Video recorder, Smart Car



- ▶ Terminal deformation prevention structure
- ▶ Detect Terminal Structure
- ▶ Push-Pull Type

Specifications

Current Rating	Contact Resistance	Insulation Resistance	Dielectric Strength	Temperature Range
0.5A/Pin	100mΩ [Max.]	1,000MΩ [Min.]	AC 500V	-40°C ~ 85°C

Mating Size & Product No.

PINS	PITCH	WIDTH	HEIGHT	LENGHT	CODE
8	1.10	11.10	1.70	7.00	MS110-C09B-C17

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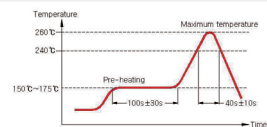
Product Specification

Ratings	Rated current	0.5A/Pin	Operating temperature range	-40°C to +85°C 1	Storage temperature range	-5°C to +40 °C (With packing)
	Rated voltage	Max 10V AC(RMS) or DC	Operating humidity range	10% to 80% RH 2	Storage humidity range	65%RH

1) Including terminal temperature rise.

2) Storage area is to be free of corrosive gases and dew formation.

Items	Specifications	Conditions
1. Contact resistance	100mΩ [Max.]	- Open circuit voltage: 20mV. - Test current: 10mA.
2. Insulation resistance	1,000MΩ [Min.]	- Test voltage: 500V d.c. - Test time: 1 minute ± 5 seconds.
3. Withstanding voltage	No flashover or dielectric breakdown	AC 500V for 1minute
4. Card insert force	1,000gf [Max.]	Insert the card at a rate of 25±3 mm/min. (actual card used)
5. Card retention force	800~1,000gf	Insert the card at a rate of 25±3 mm/min. (actual card used)
6. Durability	1) Contact resistance : After test 140mΩ Max 2) No have damage, Crack terminal junction variation and shake on product	it perform test repeat insert and withdrawal test of card with 400~600 cycle/h speed. - micro-SD : 10,000times - One cycle : 6sec (minute 10times) - Change the card every 1,000 times - After every 10 cycles blow with dry air.
7. Vibration	Discontinuity : 1.0 microsec. MAX.	- Vibration frequency range : 10~55Hz - Total amplitude : 1.5mm - Sweep ration : 10-55-10Hz / Approx 1min. - Duration : 2h each (6h in total)
8. Shock resistance	Discontinuity : 1.0 microsec. MAX.	- Acceleration : 50G (490 ^{m/s²}) - Duration : 11ms - Number of shocks : 3 both axial directions, 3 times each, 18 times in total - Test voltage : 5V d.c. - Test current : 1mA d.c.
9. Humidity	- MAX. Change from Initial contact resistance 40mΩ MAX. - Insulation resistance : 100MΩ Min	- Temperature : 40°C±2°C - Relative humidity : 90% RH to 95% RH - Duration : 96hr
10. Temperature cycle	- MAX. Change from Initial contact resistance 40mΩ MAX. - Insulation resistance : 100MΩ Min	- 40±3(°C) : 30 minutes → - 85±2(°C) : 30 minutes, 5 cycles
11. Solder heat resistance	- No have something wrong of push functions. - No have deformation and fall off. - No have something wrong outward appearance and structure.	Reflow condition. (Refer to Reflow)



Materials / Finish

Part	Materials	Finish	UL Regulation
Base	LCP	Black	UL94V-0
Terminal	Copper Alloy	Au-Pd , Ni plated	-
Cover	Stainless Steel	Ni plated	-

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SQ

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Product Drawing

